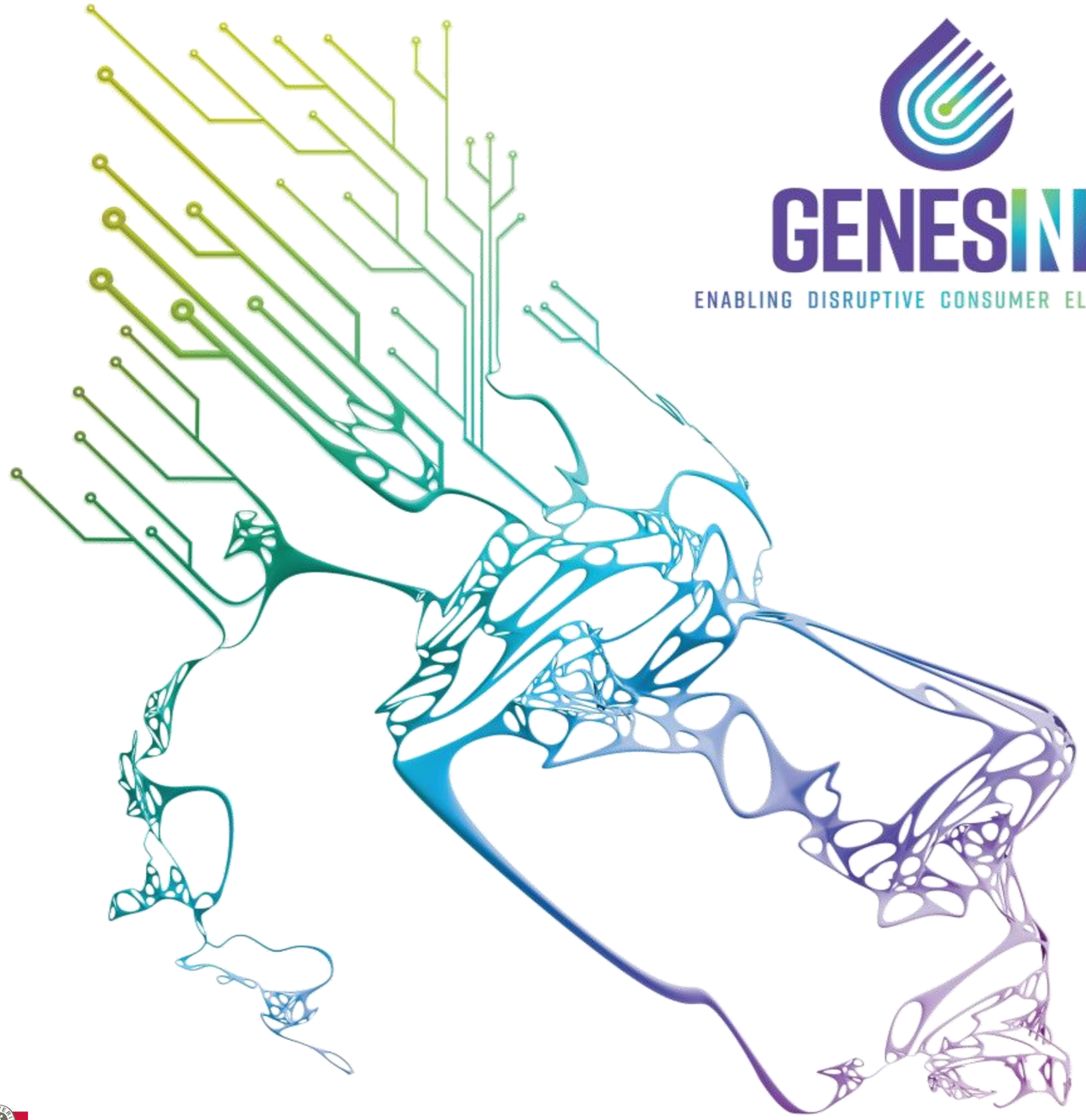


GENESINK

ENABLING DISRUPTIVE CONSUMER ELECTRONICS

Investment Opportunity

November 2022

GENESINK

Unlocking the Power of Nano-inks

4 Techonology Plaforms

Disruptive & highly-differentiated next generation of nano-inks

- Broad & immediately-available applications in major segments of industrial electronics
- Pipeline of earlier-stage innovations with initial proof-of-concept
- Ability to formulate across a broad range of metals

Demonstrated Superiority

Conclusive data in head-to-head comparison with current generation

- Positive tests & feasibility studies (in-house & in collaborations with major players)
- Fully & “immediately-integrable” into major players’ manufacturing processes

Multiple Catalysts

Multiple & advanced R&D collaboration with major players in the field

- 100% of the IP belongs to GenesInk and is fully unencumbered
- Technologies already integrated into several electronic devices
- In advanced collaboration discussions with major players in the field to develop pipeline
- News flow will attract further potential partners

Solid Foundation

Positioned for growth

- Expert team with established R&D & production capabilities
- Solid IP position (130 patents & 80 proprietary formulations)
- Positive patentability and Freedom To Operate
- Looking to raise capital to expand R&D and partnering activities + strengthen investor’s basis

GENESINK

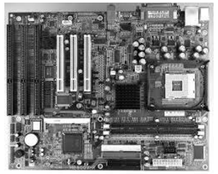
A Consumer Electronics External Innovation Engine as a Model

- Decade of proprietary fundamental & applied research in nano solutions
- Breadth and depth for continued innovation and product supply
- Already-established partnerships with major players in the field (validation of approach & results) with initial sales of raw material
- Need to accelerate product development & pool of partners

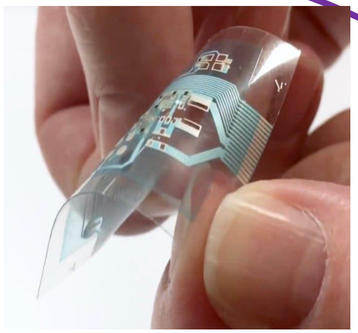
- Significant upfront payments to secure access to know-how & patents (IP) of certain technology(ies) or defined application(s) in a given field
- Significant development milestones linked to R&D collaboration agreements
- Commercial milestones & royalties linked to sales performances and intellectual property
- R&D and commercial-scale supply agreements
- Platform / asset acquisition a possibility

Our proprietary nano-inks enable transition to « anywhere connectivity »

1. We develop **flexible, transparent, light and eco-friendly specialty chemicals** - conductive and semiconductive solutions to enable the design of next generation industrial and consumers products



BEFORE



NOW

2. **We use a unique process for additive manufacturing** yielding very high conductivity for electronic components (system in package “SIP”) with no modification to clients production process

3. **We substitute heavy and polluting production techniques** such as chemical baths, with **nontoxic products** used at room temperature and normal atmosphere.

4. **We empower** additive manufacturers with better performance using **less raw material**

5. **We tailor our** solutions to our customers’ **specific needs at their manufacturing location of choice**.

An Ubiquitous Technology

Electronics needs to be small, thin, & highly conductive to adapt to any host and environment.

Today's connectivity is ubiquitous. Because we are at least **to 5x times more conductive, we are undetectable.**

Higher conductivity enables energy conservation.

We design **ultra power efficient,** conductive, nano inks, generating significantly less heat.

Legacy manufacturing is increasingly outlawed worldwide for environmental reasons.

Our solutions are designed to be sustainable and **respectful of humans and the environment.**

Only a handful of competitors able to ship at production scale

Mass production **ready!**
Our nano inks are available at **Ton scale** and **tested for industrial use**

Pluggable by design into any consumer electronics manufacturers' production processes

4 Disruptive Technology Platforms Available for Partnerships

130 patents 80 formulations

High loading metal inks

Conductive Tracks for

- FPCB
- In-Molding
- Sensors
- Silicon PV

AGFA

Dow/ Dupont

ESSILOR

Qualcomm

Low loading metal inks

Conductive Grids for

- Touch-screen
- EMI shielding
- Display
- IOT
- OPV

Patented technological Bricks for specific markets

Leader in head manufacturer

Leader in electronics market

Henkel

SAMSUNG

Heraeus

Pegatron

TSMC

Base patent family with broad technological coverage

Metal oxide semi-conductive inks

Transport Layer

- Display
- OPV
- Touch-screen
- OLED

Henkel

BASF

Hitashi

Transparent Conductive layers

W/O ITO

Meta

nano

SAMSUNG

Nissha

Leader in electronics market

Essilor

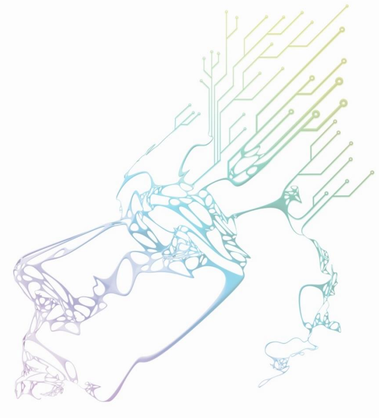
Electronics substrate supplier

- Transparent Conductive Film
- OPV
- Display
- Touch-screen
- OLED

GENESINK

4 Disruptive Technology Platforms Based on the Below IP

130 patents 80 formulations



Case Number	Publication #	Priority Date	
06795	WO2015/000796	03-juil-2013	Ink with ZnO NPs
06852	WO2015/078818	27-nov-2013	Ink with Ag NPs
06853	WO2015/078819	03-juil-2013	Dispersion with Ag NPs
07083	WO2017140712	18-févr-2016	Ink with AZO NPs
07105	WO2016184979	20-mai-2015	Ink with Ag NPs for screen-printing
07106	WO2016184975 (A1)	20-mai-2015	Ink with Ag NPs for dispersion
07171	FR3054553	01-août-2016	Ink compatible for food application
07656	WO2020120252 (A1)	13-déc-2018	Ink with Ag NPs for inkjet-printing
07657	WO2020120250 (A1)	13-déc-2018	Synthesis of WO_3 NPs and ink formulation
106754	WO2021115750 (A1)	11-déc-2019	Ink with Ag NPs for PV
106757	WO2021115748 (A1)	11-déc-2019	Ink with Ag NPs for stretchable application

- 12 Inventions
- 83 Patents granted
- 54 patent applications pending
- 1 patent recently filed
- 3 new patents being written

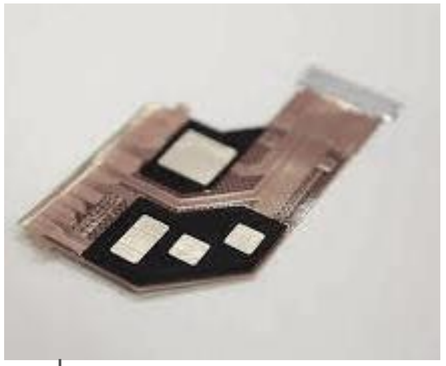
High loading silver inks

Low loading silver inks

Metal oxide semi-conductive inks

Immediate Traction Is On 6 Key Markets… 1/2

01
IC Packaging



- EMI shielding

02
TCF

- Transparent heater
- Connected glasses
- Virtual Reality

03
SENSORS IN HMI

- Printed biometric sensors
- Touch panels

$45B

EMI shielding in IC packaging

$8B

Low loading silver inks

TCF

$2B

Transparent Conductive layers
W/O ITO

SENSORS

$35B

High loading silver inks

EMI SHIELDING: *EMI Shielding Market Size, Share, Industry Report (2021-2026) (marketsandmarkets.com)*
TCF: *https://www.alliedmarketresearch.com/transparent-conductive-films-market*
Sensors: *Sensor Market Size, Share and Industry Analysis | Forecast - 2028 (alliedmarketresearch.com)*

*** When sources on the market are global, we took an amount that is representative for raw material.**

…With Varying Progress Timeline 1/2

2022		2023				2024				2025				2026			
Q3	Q4	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4

EMI shielding

Product validation → Initial Market Introduction → Market Expansion

Heraeus: Discussion of a collaboration contract

Done

Product validation → Initial Market Introduction → Market Expansion

AzureWave - Pegatron: preproduction series

Apps: metal housing replacement for EMI shielding on EMC chips (microelectronic components with high density of transistors)

***Other Key Players:** ASE, TSMC*

Sensors

Product validation → Initial Market Introduction → Market Expansion

Agfa: Initiation of a collaboration discussion

Product validation → Initial Market Introduction → Market Expansion

Qualcomm: validated product

Apps: touch screen sensors for fingerprint reader and ultra thin film transistor

TCF

Transparent conductive film

Product validation → Initial Market Introduction → Market Expansion

Meta: prototyping

Product validation → Initial Market Introduction → Market Expansion

Nissha: prototyping in a pilot line

Apps: transparent heaters in Automotive

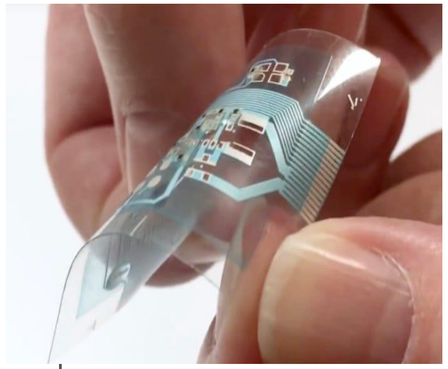
***Other Key Players**: Garmin, Smart watches manufacturer; Transition for smart glasses (IoT)

Key Players to identify in Large Display & Lighing

◆ Milestones

Immediate Traction Is On 6 Key Markets… 2/2

04
FLEXIBLE PRINTED CIRCUITS



- FPCBs for sensors in automotive

FPCBs

$6B

High loading silver inks

05
PV

- Printed fine conductive tracks
- Busbars

SILICON PV
ORGANIC PV

$82B

High loading silver inks

06
IoT

- Antenna
- Smart glasses

IoT

$104B

High loading silver inks

$192B

Flexible printed circuit: *Flexible Printed Circuit Board Market is estimated to Rise (globenewswire.com)*
PV: *Solar Photovoltaic [PV] Market Share, Growth & Trends, 2028 (fortunebusinessinsights.com)*
IOT: *IoT Connectivity Market size worth $ 693.26 Billion, Globally, by 2028 at 20.33% CAGR: Verified Market Research® (prnewswire.com)*

*** When sources on the market are global, we took an amount that is representative for raw material.**

…With Varying Progress Timeline 2/2

2022		2023				2024				2025				2026			
Q3	Q4	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4

FPCBs
Flexible printed circuits

Product validation → Pilot production & demonstration → Initial Market Introduction → Market Expansion

Continental: validated product
Apps: in-molded FPCBs for sensors in Automotive

****Other Key Players**: Agfa*

PV
Photovoltaics

Done

Product validation → Pilot production & demonstration → Initial Market Introduction → Market Expansion

EMC: Organic PV
Apps: busbars and finger grids in PV

****Other Key Players**: Nanobit*

Product validation → Pilot production & demonstration → Initial Market Introduction

Italian electricity supplier: Silicon PV
Apps: busbars and finger grids in PV

***Key Players:** Dupont

IoT
Internet of Things

Done

Product Validation → Pilot production & demonstration → Initial Market Introduction → Market Expansion

EssilorLuxottica: smart glasses
Apps: conductive busbars for ophthalmics

Invention → Concept validation → Product validation → Pilot production & demonstration

Medisur: point-of-care devices
Apps: conductive busbars for Health Diagnostic Tests

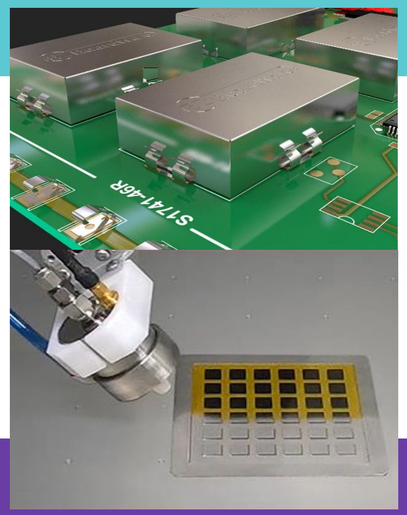
◆ Milestones

Short term market application : EMI Shielding

Validation product on-going: Heraeus

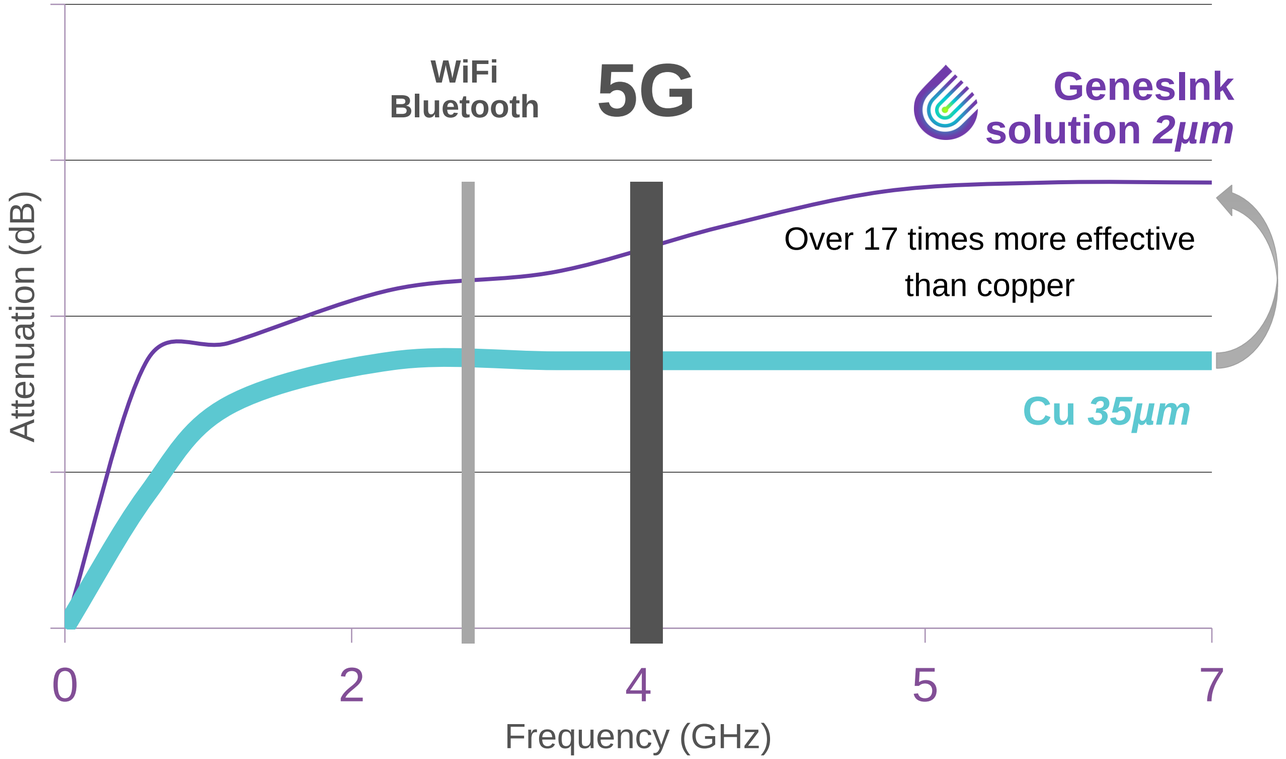
Replacing rigid metal housing by a single-step "direct spray coating" of a silver solution **1000 times thinner** allows designers and manufacturers to embed electronics everywhere

From 370 mg to 10 mg of weight



EMI SHIELDING
$8B TAM IN 2027
CAGR 4%

High adhesion on all substrates on top and sidewalls.



EMI SHIELDING: *EMI Shielding Market Size, Share, Industry Report (2021-2026) (marketsandmarkets.com)*

* When sources on the market are global, we took an amount that is representative for raw material.

Market application: Transparent Heaters

Product Validated: NISSHA

GENESINK Products: TCF =**Transparent Conductive Film**
Printed patternable heater

Advantages: Fast and homogeneous heating, high transparency, Flexibility, low power, low CAPEX

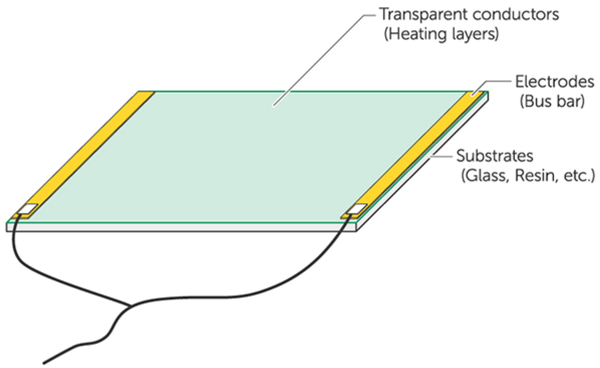
Sheet resistance	50 ± 5 Ω/□
Transparency	92 ± 2 %
Viscosity(20°C)	1200 ± 100 mPa.s
density	1
Roughness (Rq)	2 - 5 nm
Thickness	600 nm
Sintering Conditions	RT 90s + 90°C 5min

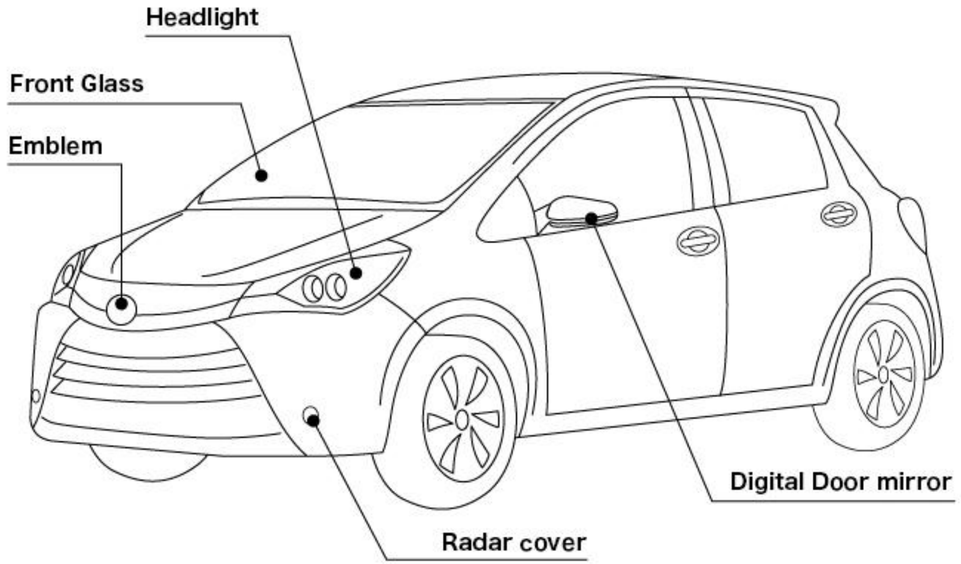
KEY NUMBERS

TAM

Transparent heater

$1,7B
IN 2027
CAGR 7,2%





Transparent heater : https://www.marketsandmarkets.com/Market-Reports/flexible-heater-market-51373429.html

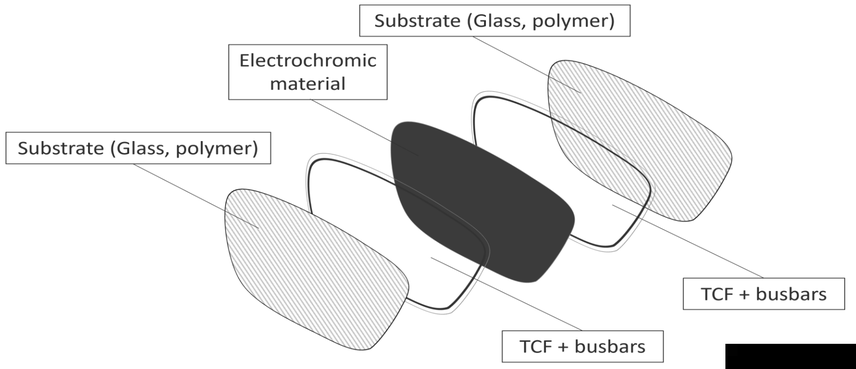
*** When sources on the market are global, we took an amount that is representative for raw material.**

Market Application: Intelligent Eyewear AR/VR

Pilot Production: EssilorLuxottica

GENESINK Products:

- Silver conductive tracks through 3D dispensing
- **Transparent Conductive Film**



Sheet resistance	15 ± 5 Ω/□
Transparency	≥ 90 %
Viscosity(20°C)	40 ± 5 mPa.s
density	0,8
Roughness (Rq)	< 7 nm
Thickness	200 nm
Sintering Conditions	RT 90s + 90°C

Optical Market

$25.9B
IN 2028
CAGR 6%

AR/VR

$4,9B
IN 2028
CAGR 16%

Optical: https://www.fortunebusinessinsights.com/industry-reports/eyewear-market-101749
AR/VR : https://www.alliedmarketresearch.com/ar-and-vr-smart-glasses-market-A11110

*** When sources on the market are global, we took an amount that is representative for raw material.**

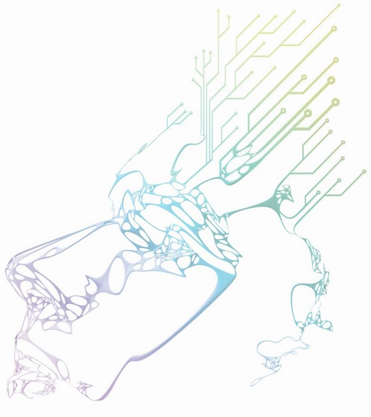
Video of Essilor-Luxottica innovation with our product

Market application: IoT & Antennas

Validation on-going AIRBUS HELICOPTERS

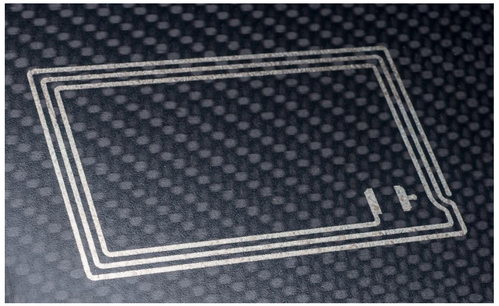
IoT

$6,3 Mds IN 2025 CAGR 55,4%



- **Increased adoption of Industry 4.0 raises the demand for *low latency connectivity*, *increasing number of connected IoT devices* and *growing data traffic* are driving the 5G IoT market**

- **North America is expected to hold the largest 5G IoT market share during the forecast period, followed by Europe and then Asia Pacific.**



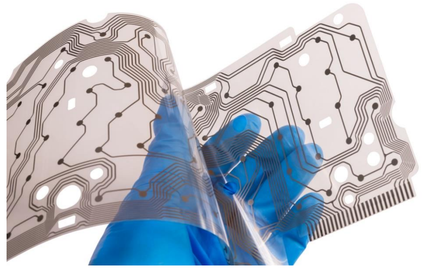
- ✓ Various applications dedicated to IoT and 5G connectivity:
  - ❑ Antennas and sensors
  - ❑ Stretchable and wearable electronics
  - ❑ In-mold electronics
  - ❑ EMI shielding
- ✓ Compatible with flexible, stretchable, and rigid substrates : polymers, papers, cellulose, glass, composites and silicon

5G frequency bands :

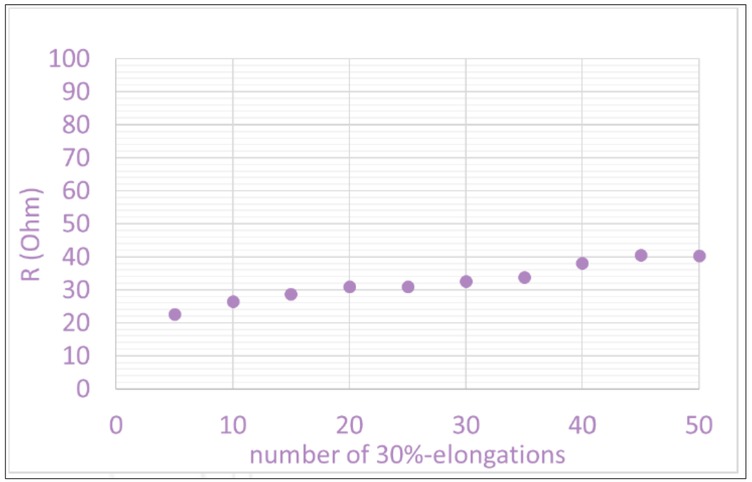
GenesInk's nanomaterials are adapted to all types of antennas and frequencies (RFID, 4G, wifi, cellular, etc.)

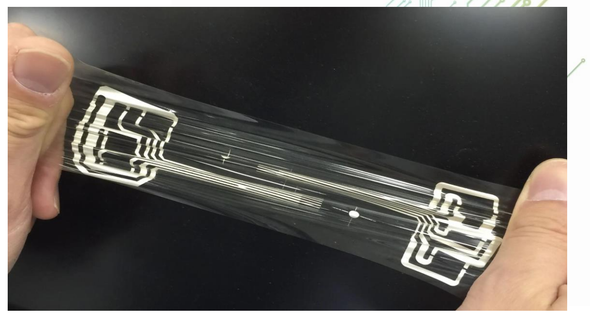
Market Application: Flexible Printed Circuits

Validation on-Going



	Smart Screen s
Silver content (%)	55
Viscosity (cPs)	13 500 - 17 500 @40s-1
Density (g/mL)	2
Resistivity @150°C (µOhm.cm)	25





Streachable application :
Wearable, smart clothing, wearable electronics, automotive and aeronautics appliances.

Offers possibility to print on various substrates including **plastics**

Flexibility due to **thickness, adhesion** and **nanostructure**

Offers a 2 mm bending radius

Easier to integrate in a final system

Easier to integrate in a final systemEnables **new device designs**

FPCB

$55B
IN 2031
CAGR 10,3%

KEY NUMBERS TAM

Stretchable electronic

$4,8B
IN 2029
CAGR 25,2%

FPCB: https://www.globenewswire.com/en/news-release/2022/06/16/2464132/0/en/Flexible-Printed-Circuit-Board-Market-is-estimated-to-Rise-at-a-CAGR-of-10-3-during-the-Forecast-Period-TMR-Study.html
Stretchable Electronic: https://www.globenewswire.com/news-release/2022/08/11/2496873/0/en/Stretchable-Electronics-Market-Growing-at-a-Significant-Rate-CAGR-of-25-2-to-reach-USD-4-80-billion-by-Exactitude-Consultancy.html

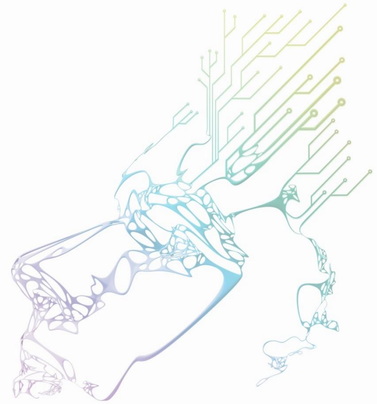
17

Market application: Solar Panels

Validation on-going: Italian Energy Supplier

PV

$50B
IN 2025
CAGR 5%



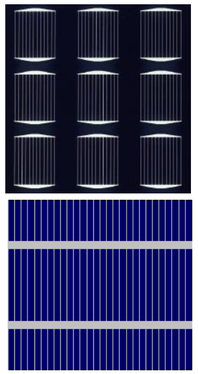
GENESINK Products: Silver Cell strips and interconnects for Si PV through screen-printing required **LOW CAPEX requirement**

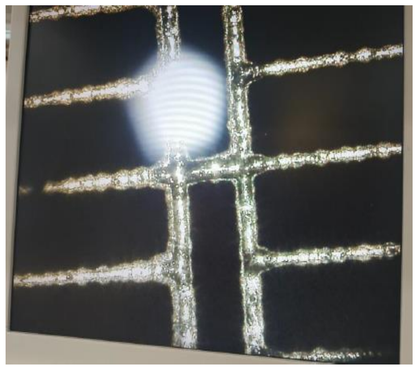
Genesink solution below 200C by consuming 75% less material

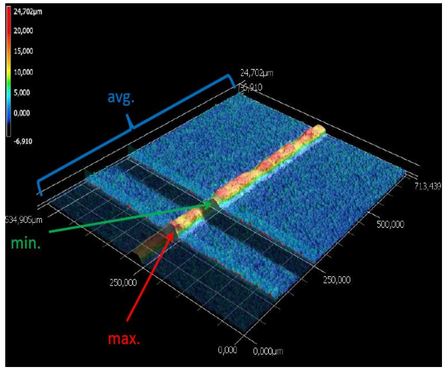
Busbars of standard solar cells

Front grid dingers: 6 µm and width 60 µm

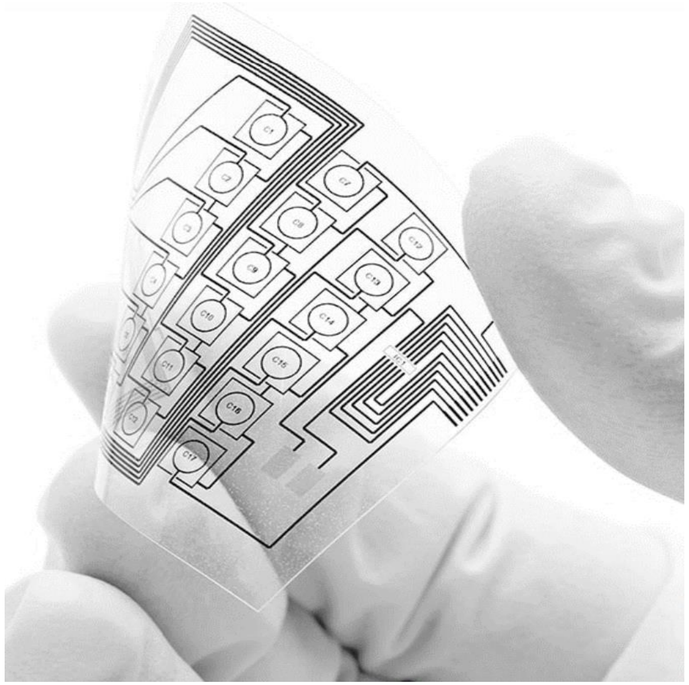
Busbar thickness: 6 µm and width: 1 mm







Properties	GenesInk solution
Voc [V]	0.73
Isc [A]	9.3
FF [%]	>70
Eff. [%]	20
R (mΩ/□)	10



Future Market Application : Connected Health and Medical Tests

Project initiated: Medisur

- **GENESINK Products:** Silver conductive circuit
- **Target products :** optical sensors, biosensors, touch sensors,

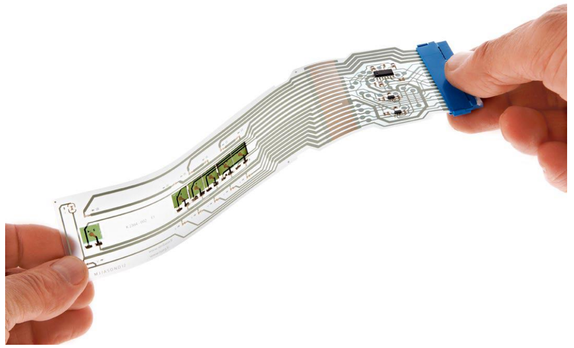
KEY NUMBERS

TAM

Sensors

$53B
IN 2027
CAGR 9%

	Smart Screen F
Silver content (%)	55
Viscosity (cPs)	5000 - 7000 @40s-1
Density (g/mL)	2
Resistivity @150°C (µOhm.cm)	5



Sensor Market Size, Share and Industry Analysis | Forecast - 2028 (alliedmarketresearch.com)

ERRC* Analysis – What Makes Us Unique

Eliminate	Reduce
Production Process steps Waste in Production Temperature constraints All the Carcinogenic Mutagenic Reprotoxic (CMRs) products	Production lead-time Material consumption Energy consumption Delivery time Environmental footprint
Raise	**Create**
Conductivity allows miniaturization and ubiquity, Exclusive license allows to eliminate competition Flexibility, lightweight, transparency allow to be everywhere Increase product stability, allow storage Hyper specialty chemicals for specific customization allow customer differentiation.	Conductivity allows to create new products Flexibility, lightweight, transparency allows to create new products New design service (Marketplace)

ERCC Grid From the Blue Ocean Strategy Best Seller book

Leadership team combines materials science & electronics experience

CORINNE VERSINI
Founder, CEO
- 30+ years in the electronics industry
- Sales and Procurement Director at IBM & STMicroelectronics
- Elected “Engineer of the year” in 2016 by "The Academy of Science”

BENJAMIN DHUIEGE
CTO
- 10 years as Head of R&D in startups
- PhD in Material Sciences with specialization in polymers and formulation

EMMANUELLE PIETRI
Customer Support
- 15 years as Production manager
- Expert in QHSE (Quality, Health, Safety & Environment)
- Experienced in ERP tool

PASCALE BRUYAT
External CFO
- 30-year experience in finance and audit
- 5 years as auditor, 15 years CFO in the semiconductor market
- 10 years as a fractioned CGFO for SME’s and mid-size companies

18 talented people

STÉPHANIE VILLECROZE
Back office leader

GRÉGOIRE STAELENS
Electronic specialist

Governance Team With Experienced People in Innovation

Board

ALBERTO HADDAD
Chairman
Entrepeneur, Investor

AARON MICHELIN
CEO Corporatum Oy,
Entrepeneur, Investor

JACQUES SENECA
– Non-Exec Strategic Advisory & Investment
Gemplus/Gemalto EVP

Strategic Advisors

VICTORIA HERNANDEZ
Business Angel Caixa Board Member, former CEO Orange Spain

THIBAUD LE SEGUILLON
CEO, Industrya

JEAN-YVES GOMEZ
Founder and CEO ISORG

JEAN-PIERRE GLOTON
Co-founder GEMPLUS & JPG Pack manager

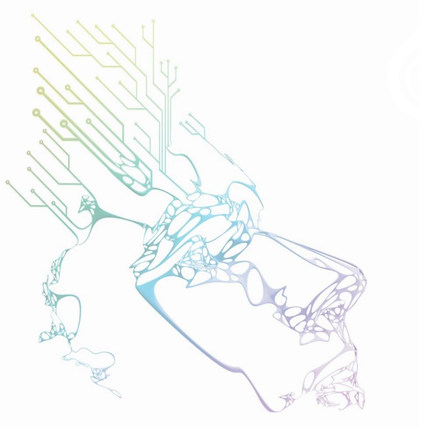
Scientific Advisors

DR BEATRICE-HELENA ARIANO
Life Science Forum Basel
President & Member of the Board

DR GIOVANNI NISATO
Managing Director,
Innovation Horizons GmbH

DR. ESRA KÜÇÜKPINAR
Scientist at Fraunhofer for Process Engineering and Packaging (IVV)

VALÉRIE SERRADEIL
Innovation & Collaboration
R&D Programs Manager at
ST Microelectronics



Why Invest In Genesink

- One of a handful of companies with the know-how to transform global electronics NOW
- 4 Platforms that enable ubiquitous connectivity across a broad number of industries representing a $200 billion+ opportunity
- Genesink’s nano-inks are a game-changer for performance, transparency, sustainability and weight
- Marquis list of partners in test demonstrates the pertinence of the need across industry mix
- Business model underpinned by licensing fees, joint R&D, recurring royalty streams and large-scale recurring revenues
- Asset light strategy means focus on immediate value creation for significant return on investment.

Reach us

www.genesink.com

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The future of electronics is now: Flexible, Eco-friendly, Light & Transparent.

For more information contact me corinne.versini@genesink.com

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Thank you for your attention

Version 001 of 16/11/2022
Modified by Nicolas Olive

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